# Bill of Materials

<table>
<thead>
<tr>
<th>Designator</th>
<th>Value</th>
<th>Quantity</th>
<th>Description</th>
<th>DigiKey PN</th>
</tr>
</thead>
<tbody>
<tr>
<td>EVM</td>
<td>EVM430-FR6989</td>
<td>1</td>
<td>EVM430-FR6989 evaluation kit</td>
<td></td>
</tr>
<tr>
<td>PCB</td>
<td>TIDM-TMR-WATERMTR</td>
<td>1</td>
<td>TMR Sensor board PCB</td>
<td></td>
</tr>
<tr>
<td>ESI</td>
<td>SFH11-PBPC-D08-ST-BK</td>
<td>1</td>
<td>Connector</td>
<td>S9196-ND</td>
</tr>
<tr>
<td>U1</td>
<td>AAT001-10E</td>
<td>1</td>
<td>NVE TMR sensor</td>
<td>391-1065-1-ND</td>
</tr>
<tr>
<td>Magnet</td>
<td>12249</td>
<td>1</td>
<td>NVE Split Pole Magnet</td>
<td></td>
</tr>
</tbody>
</table>
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